

● Stack Up ●

Propose PCB Stack Up			Impedance		
Layer	Type	Thickness (mil)	Differential	Theory value	Ref
	Top side solder mask	0.70 mils			
L1	TOP copper+plating	1.58 mils	5/5/5 mils · 100Ω±5% adjust 4/6/4 · 100Ω±5%	98.66Ω	L2
	Prepreg	4.50 mils			
L2	PWR copper	2.80 mils			
	core	6.00 mils			
L3	Signal copper	0.70 mils	5/5/5 mils · 100Ω±5% adjust 3.6/6.4/3.6 · 100Ω±5% Copper 0.5oz	97.94Ω	L2 & L4
	Prepreg	4.50 mils			
L4	PWR copper	2.80 mils			
	core	6.00 mils			
L5	Signal copper	0.70 mils	5/5/5 mils · 100Ω±5% adjust 3.6/6.4/3.6 · 100Ω±5% Copper 0.5oz	97.94Ω	L4 & L6
	Prepreg	4.50 mils			
L6	PWR copper	2.80 mils			
	core	3.00 mils			
L7	PWR copper	2.80 mils			
	Prepreg	4.50 mils			
L8	PWR copper	2.80 mils			
	core	3.00 mils			
L9	PWR copper	2.80 mils			
	Prepreg	4.50 mils			
L10	Signal copper	0.70 mils	5/5/5 mils · 100Ω±5% adjust 3.6/6.4/3.6 · 100Ω±5% Copper 0.5oz	97.94Ω	L9 & L11
	core	6.00 mils			
L11	PWR copper	2.80 mils			
	Prepreg	4.50 mils			
L12	Signal copper	0.70 mils	5/5/5 mils · 100Ω±5% adjust 3.6/6.4/3.6 · 100Ω±5% Copper 0.5oz	97.94Ω	L11 & L13
	core	6.00 mils			
L13	PWR copper	2.80 mils			
	Prepreg	4.50 mils			
L14	Bottom copper+plating	1.58 mils	5/5/5 mils · 100Ω±5% adjust 4/6/4 · 100Ω±5%	98.66Ω	L13
	Bottom side solder mask	0.70 mils			
TOTAL		91.26 mils 2.32 mm	Suggested Thickness 0.094" +/-0.010"		

Picture :

